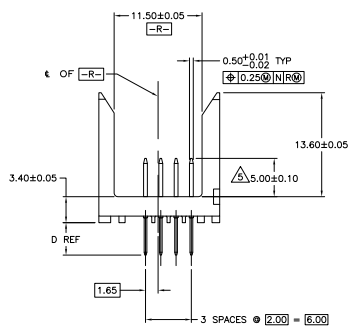
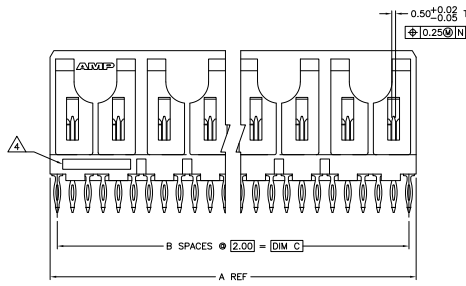
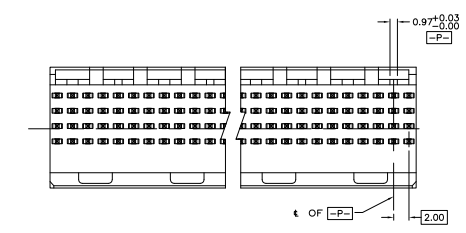
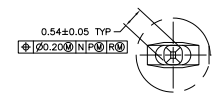


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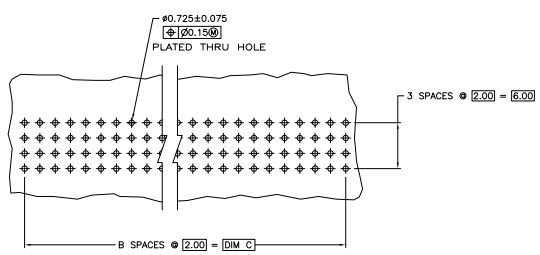
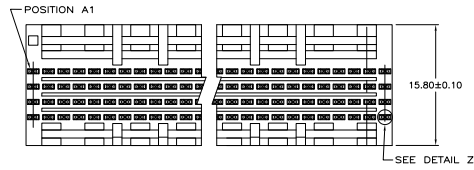
REVISIONS			
REV	DATE	DESCRIPTION	BY
AD	00	REVISED PER ECO-11-00633	299M11 RK HMR



- △ HOUSING MATERIAL: LIQUID CRYSTAL POLYMER PER ASTM D5138 LCP000 G30A 32250.
- △ CONTACT MATERIAL: PHOSPHOR BRONZE.
- △ CONTACT FINISH:
 UNDERPLATE (ENTIRE CONTACT):
 0.00127 MIN NICKEL PER SAE-AMS-QQ-N-290.
 ON MATING SURFACES:
 CONFORMS TO ALL TESTING SPECIFIED FOR TELCORDIA UNCONTROLLED ENVIRONMENT.
 ON LEADS
 0.0006 MIN TIN PER ASTM B 545 OVER UNDERPLATE.
 LUBRICATION (MIN MATING SURFACES):
 SURFACE CONDITIONER AFTER PLATING.
- △ PART MARKING, LOCATED APPROXIMATELY AS SHOWN.
- △ DIMENSION APPLIES WHEN SEATED ON PRINTED CIRCUIT BOARD.
- △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



DETAIL Z
 SCALE 20:1



RECOMMENDED CIRCUIT PATTERN
 PER IPC-D330 TYPE II, CLASS C
 (COMPONENT SIDE)

OBSOLETE	4.25	58.00	29	59.88	120	5536514-6
△	4.25	72.00	35	71.88	144	5536514-5
	4.25	94.00	47	95.88	192	5536514-4
	4.25	46.00	23	47.88	96	5536514-3
	4.25	22.00	11	23.88	48	5536514-2
	4.25	10.00	5	11.88	24	5536514-1

THIS DRAWING IS A CONTROLLED DOCUMENT				TE Connectivity	
REV	DATE	DESCRIPTION	BY	CHKD	APP'D
AD	00	REVISED PER ECO-11-00633	299M11	RK	HMR